Applicable	e standard												
Rating Coperating temperature rar Operating humidity range Storage			-55 °C to +105°C (Note1) 20% to 80% (Note2)						AWC 16	AVA/C 18	AVAIC 20	010	
		nge				Current	:	1	15A	13A	11A	Av	9A
			-10 °C to +60°C (Note3)						10,1	10/1	100		
	temperature rai Storage	nge	40% to 7	70% (Noto2)				2	14A	12A	10A		8A
	humidity range		40% 10 /	10% (Notes)				3	12A	10A	8A		7A
Applicable co		onnector	DF63-*	DF63-*S-3.96C				4	10A	10A 8A 7A			6A
	Voltage		AC/DC	630V									
		Ra	Rated Voltage Rated Current			t	Overvoltage Category IP-Degree						
UL,C-UL		600V AC/DC		See above				 π IP00			-	1	
			See above Specification			000							
1+	om	1	Tost mo	ons	S Requirements								
Construction											QI	AI	
General examination		Visually and by measuring instrument.					According to drawing.						X
Marking		Confirmed visually.											X
Electric c	haracterist	tics											
Contact resistance		20mV MAX, 1mA (DC or 1000Hz).					10 mΩ MAX.						—
Insulation resistance		500 V DC.				100	1000 MΩ MIN.					Х	_
Voltage proof		1500 V AC for 1 min.				No	No flashover or breakdown					X	_
Mechanic		eristics				110	naone					Λ	
Mechanical	operation	50 times insertion and extraction.				() (2)	(1) Contact resistance: 20 m $\Omega$ MAX. (2) No damage, crack or looseness of parts.						-
Vibration		Frequency 10 to 55 Hz, single amplitude					(1) No electrical discontinuity of 1 $\mu$ s.						—
Chaste		0.75 mm, at 10 cycles for 3 direction.				21	(2)No damage, crack or looseness of parts.						
SNOCK		490 m/s <sup>2</sup> c	490 m/s <sup>-</sup> duration of pulse 11 ms at 3 times each for 3 both axial directions.					ectrical dis	continuity of	$1 \mu$ S.		Х	_
Environme	ental charac	teristics					to dui	lage, oracle		or parto.			l
Damp heat Exposed			l at 40 ± 2°C , 90 to 95 %, 96 h.				①Contact resistance: 20 m Ω MAX. X –						
(Steady state)		(After leaving the room temperature for 1-2h.)				(2) (3)	②Insulation resistance: 500 MΩ MIN. ③No damage, crack or looseness of parts.						
Rapid change of temperature		Temperature -55°C→ +85°C				1	①Contact resistance: 20 m Ω MAX.						—
		Time 30min→ 30min				21	(2)Insulation resistance: 1000 M $\Omega$ MIN.						
		(The transferring time of the tank is 2-3 min)				G	One damage, crack of looseness of parts.						
		(after leaving the room temperature for 1-2h.)											
Resistance to Soldering heat		1)Solder bath method					Such as impaired function , no deformation of						
		260°c for in immersion , duration, 5s.											_
2)N 5		2)Manual soldering											
		Solderin	Soldering iron temperature :300°C,										
		No strer	ig time :38.										
Solderability		Soldered	Soldered at solder temperature,				A new uniform coating of solder shall cover						
245°c for Note 1: Include the temperature rising by o			or in immersion, duration, 5 s.				minimum of 95 % of the surface being immersed. $X = -$						
Note 2: No cor	ndensing.												
Note 3: Apply 1	to the condition of ounted on PCB,	of long term operation te	storage for unused pro	oducts before mou ty range is applied	inted I for ir	on PCB.	rage d	uring trans	portation.				
	,			5 5 5 1 1			J	3					
Course		Descript	tion of rovicions			Deciano	4	1		aalrad		De	
	t	Descript			Designed						20101000		
Remarks			S-H-00005518 10. KUR			. Kuruma			<u>م</u>	HS OKAWA		20191202	
							-	Checke	d T	TIS. UKAWA	ΔN	2018	0129
							┝		d T	S KUMAZAW	A	2010	0129
Unless otherwise specified, refer to IE			EC 60512.				Drawn		<u> </u>	S. KUMAZAW	AWA 2018012		0129
Note QT:Qualification Test AT:Assurance Test X:Applicable Test					Dra	Drawing no.			ELC-378620-01-00				
HRS		Specification sheet				Part no.		DF63M-*P-3.96DSA(01)					
	1						Г	<b>_</b>					

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CL680-

Code no.

FORM HD0011-2-1

Hirose electric co., ltd.